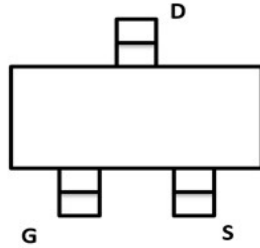
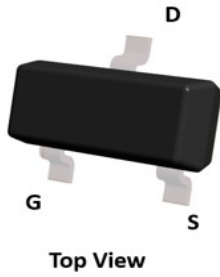
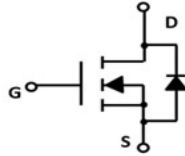


N-Channel Enhancement Mode Field Effect Transistor



SOT-23-3L



Product Summary

- V_{DS} 60V
- I_D 5.0A
- $R_{DS(ON)}$ (at $V_{GS}= 10V$) <44mohm
- $R_{DS(ON)}$ (at $V_{GS}= 4.5V$) <49mohm

General Description

- Trench Power MV MOSFET technology
- High density cell design for Low $R_{DS(ON)}$

Applications

- PWM application
- Load switch

■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	V_{DS}	60	V
Gate-source Voltage	V_{GS}	± 20	V
Drain Current	I_D	$T_A=25^\circ\text{C}$ @ Steady State	5.0
		$T_A=70^\circ\text{C}$ @ Steady State	4.0
Pulsed Drain Current ^A	I_{DM}	25	A
Total Power Dissipation @ $T_A=25^\circ\text{C}$	P_D	2.5	W
Thermal Resistance Junction-to-Ambient @ Steady State ^B	$R_{\theta JA}$	50	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	$^\circ\text{C}$

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJL05N06AL	F2	6005.	3000	30000	120000	7" reel



YJL05N06AL

■ Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	1.0	1.5	2.5	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D =5.0A		35	44	mΩ
		V _{GS} = 4.5V, I _D =4.0A		39	49	
Diode Forward Voltage	V _{SD}	I _S =5.0A, V _{GS} =0V		0.8	1.2	V
Maximum Body-Diode Continuous Current	I _S				5.0	A
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =30V, V _{GS} =0V, f=1MHZ		1018		pF
Output Capacitance	C _{oss}			70		
Reverse Transfer Capacitance	C _{rss}			62		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =30V, I _D =10A		26.4		nC
Gate Source Charge	Q _{gs}			5.4		
Gate Drain Charge	Q _{gd}			6.5		
Reverse Recovery Charge	Q _{rr}	I _F =20A, di/dt=500A/us		11.7		ns
Reverse Recovery Time	t _{rr}			23		
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DD} =30V, I _D =2A, R _L =1Ω R _{GEN} =3Ω		10		ns
Turn-on Rise Time	t _r			20		
Turn-off Delay Time	t _{D(off)}			29		
Turn-off Fall Time	t _f			21		

A. Pulse Test: Pulse Width ≤ 300us, Duty cycle ≤ 2%.

B. R_{θJA} is the sum of the junction-to-lead and lead-to-ambient thermal resistance, where the lead thermal reference is defined as the solder mounting surface of the drain pins. R_{θJL} is guaranteed by design, while R_{θJA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.



■ Typical Performance Characteristics

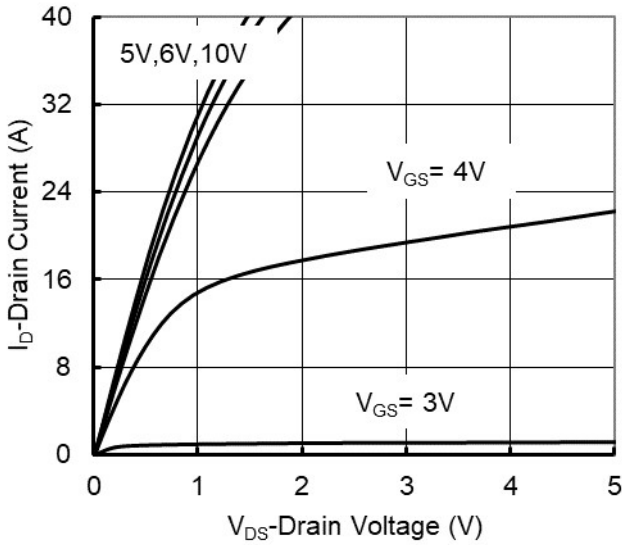


Figure 1. Output Characteristics

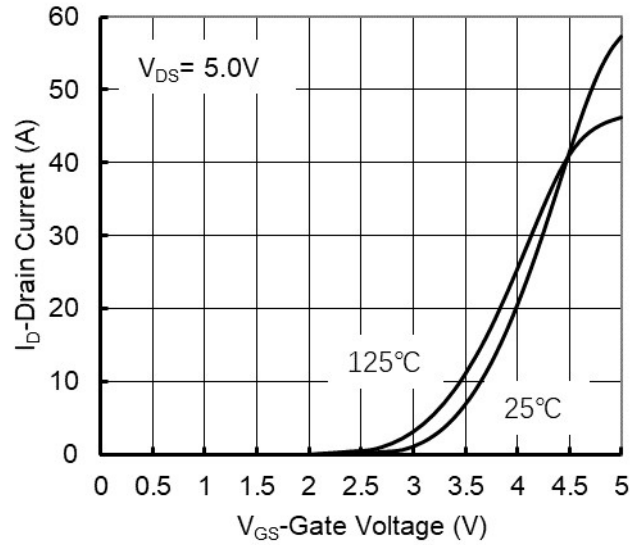


Figure 2. Transfer Characteristics

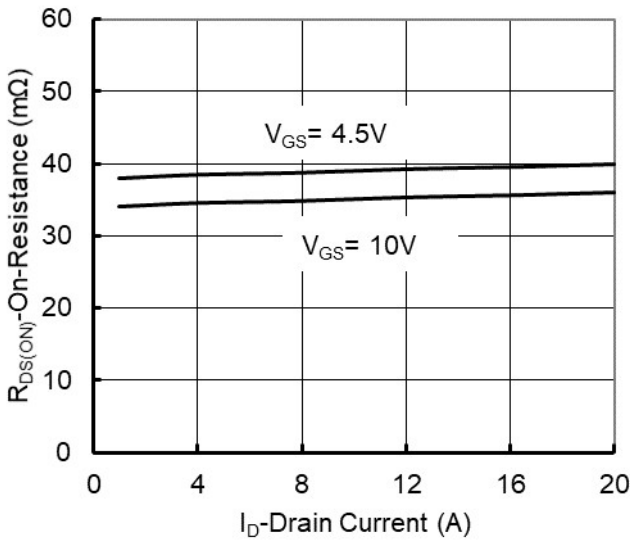


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

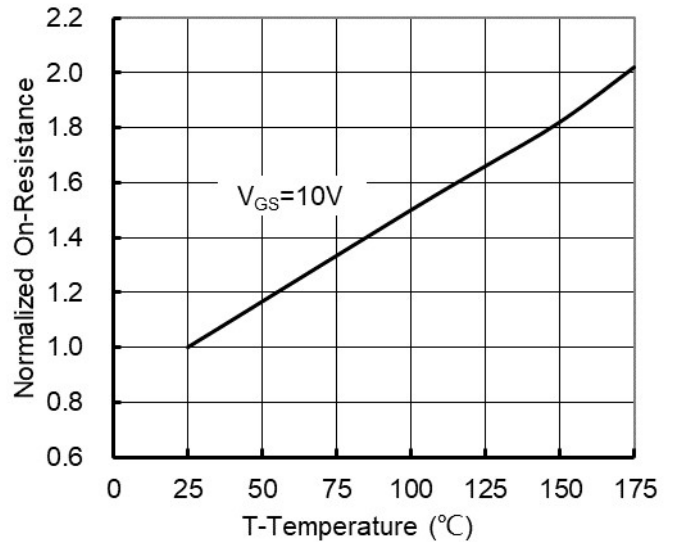


Figure 4. On-Resistance vs. Junction Temperature

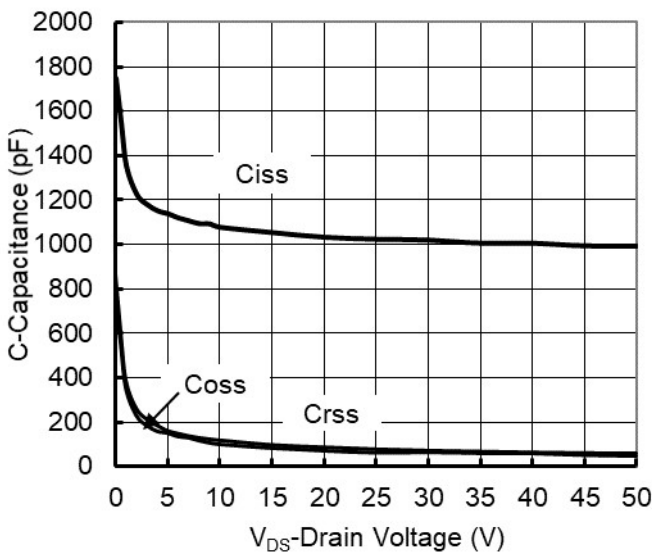


Figure 5. Capacitance Characteristics

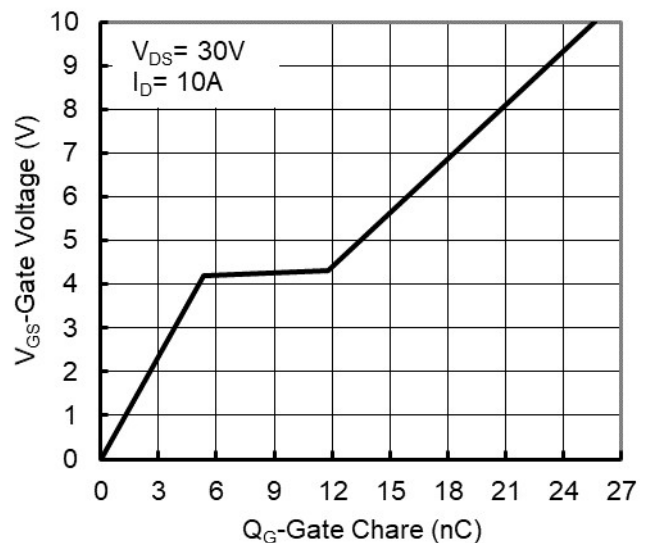


Figure 6. Gate Charge



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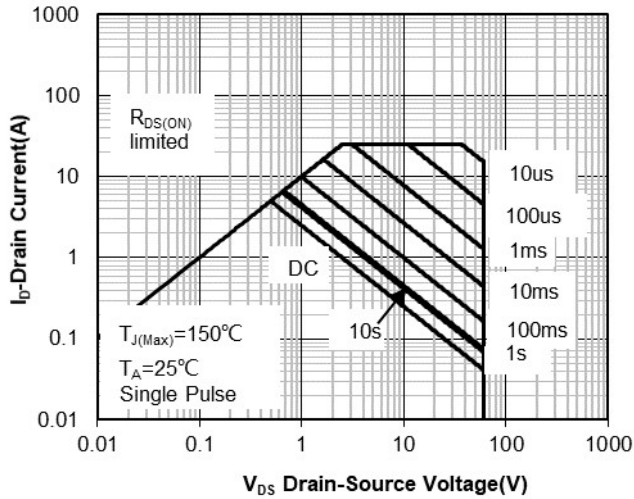


Figure 7. Safe Operation Area

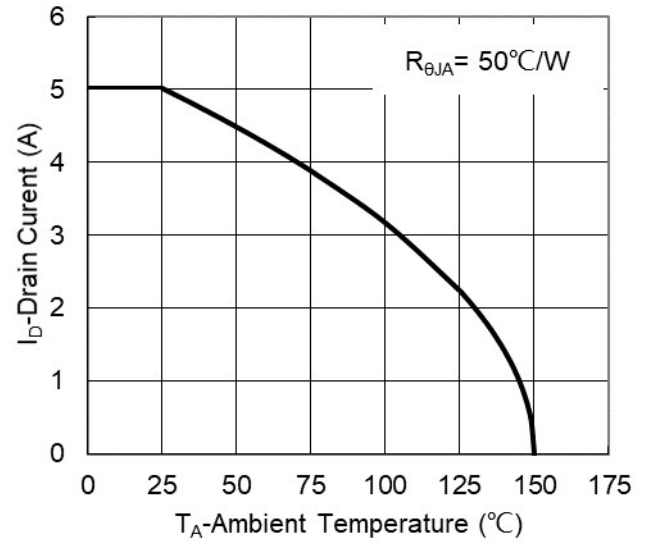


Figure 8. Maximum Continuous Drain Current vs Ambient Temperature

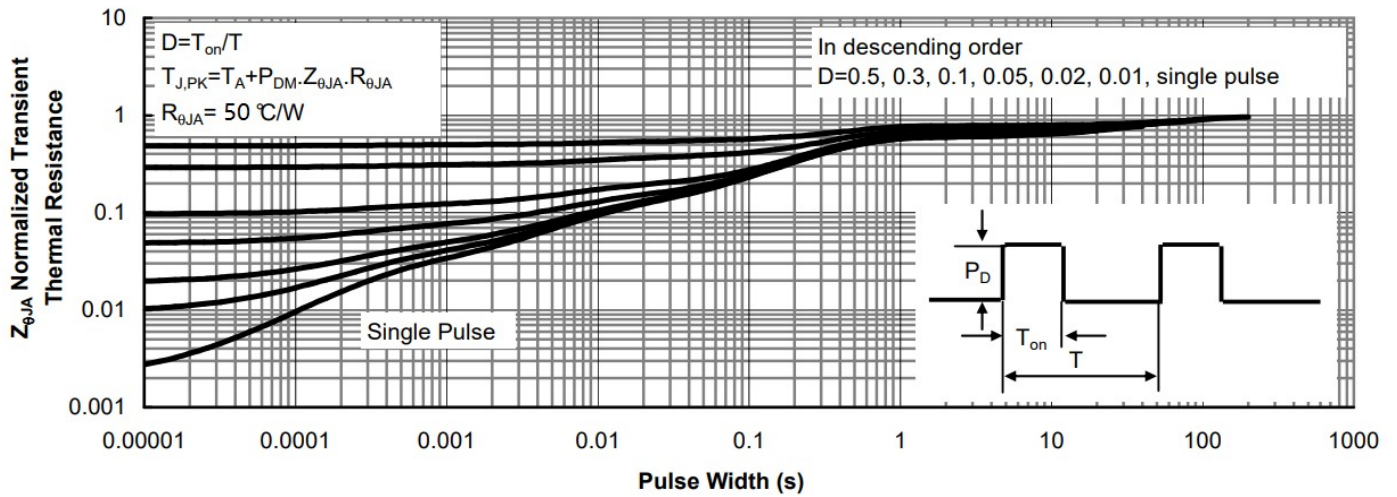
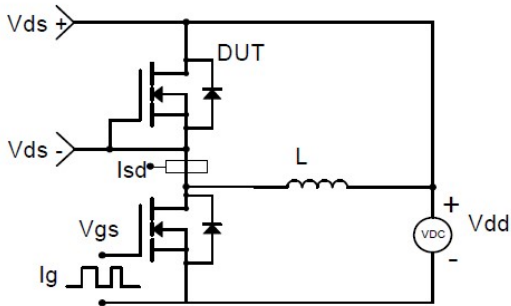


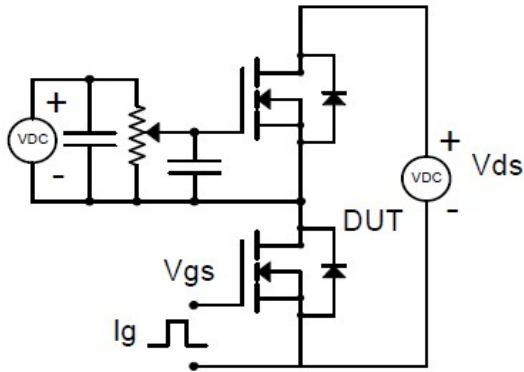
Figure 9. Normalized Maximum Transient Thermal Impedance



Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Gate Charge Test Circuit & Waveform

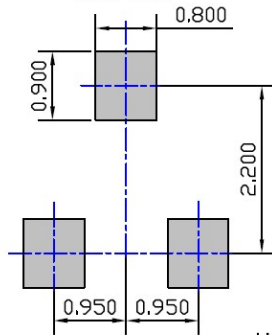
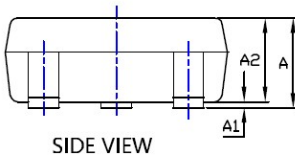
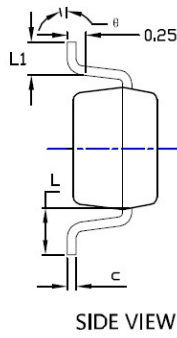
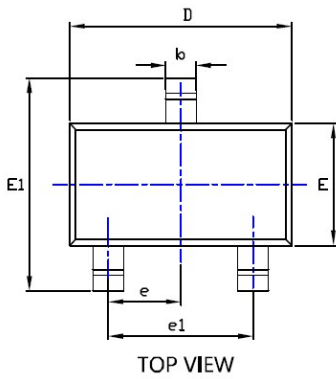


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



YJL05N06AL

■SOT-23-3L Package information



UNIT: mm

SYMBOL	DIMENSIONS					
	INCHES			Millimeter		
	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.
A	0.041	---	0.049	1.050	---	1.250
A1	0.000	---	0.008	0.000	---	0.200
A2	0.041	0.043	0.045	1.050	1.100	1.150
b	0.012	0.016	0.020	0.300	0.400	0.500
c	0.004	---	0.008	0.100	---	0.200
D	0.111	0.115	0.119	2.820	2.920	3.020
E	0.059	0.063	0.067	1.500	1.600	1.700
E1	0.104	0.110	0.116	2.650	2.800	2.950
e	0.037TYP			0.950TYP		
e1	0.071	0.075	0.079	1.800	1.900	2.000
L	0.024REF			0.600REF		
L1	0.012	0.018	0.240	0.300	0.450	0.600
θ	0°	---	8°	0°	---	8°

NOTE:
 1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
 2. TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
 3. THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.



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